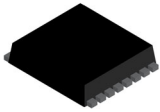
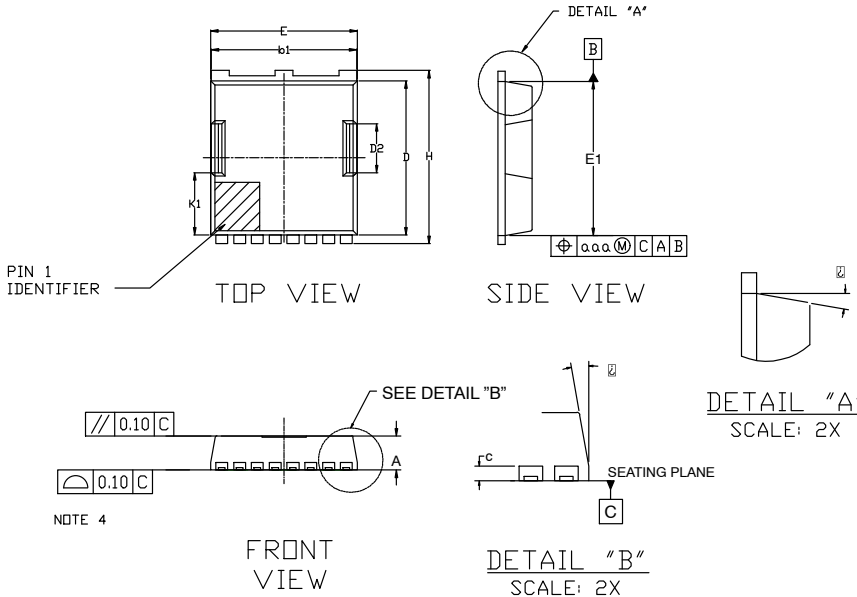


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



## H-PSOF8L 9.90x10.38x2.30 CASE 100BQ ISSUE O

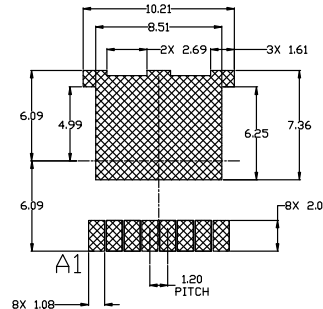
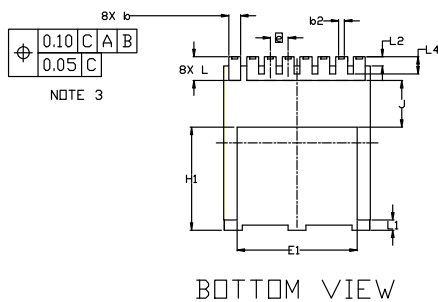
DATE 20 SEP 2022



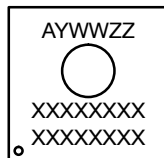
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION  $b$  APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. PROFILE TOLERANCE APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. DIMENSIONS  $D$  AND  $E$  DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
6. SEATING PLANE IS DEFINED BY THE TERMINALS.  $A1$  IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
7. A VISUAL INDICATOR FOR PIN 1 MUST BE LOCATED IN THIS AREA.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	2.20	---	2.40
$b$	0.70	---	0.90
$b1$	9.70	---	9.90
$b2$	0.42	---	0.50
$c$	0.40	---	0.60
$D$	10.28	---	10.58
$D2$	3.10	3.30	3.50
$E$	9.70	9.90	10.10
$E1$	7.90	8.10	8.30
$e$	1.20 BSC		
$H$	11.48	11.68	11.880
$H1$	6.75	6.95	7.15
$N$	8		
$J$	3.00	3.15	3.30
$K1$	3.98	4.18	4.38
$L$	1.40	1.60	1.80
$L1$	0.60	0.70	0.80
$L2$	0.50	0.60	0.70
$L4$	1.00	1.15	1.30
$\theta$	4°	7°	10°



### GENERIC MARKING DIAGRAM\*



- A = Assembly Location
- Y = Year
- WW = Work Week
- ZZ = Assembly Lot Code
- XXXX = Specific Device Code

\* For additional information on our Pb-Free strategy and soldering details, please download the [ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D](#).

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>H-PSOF8L 9.90x10.38x2.30</b>	<b>PAGE 1 OF 1</b>

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